

THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: Yoshihisa MATSUBARA, et al.
Filed: **Concurrently herewith**
For: METHOD FOR MANUFACTURING SEMICONDCUTOR....
Serial No.: **Concurrently herewith**

April 23, 2001

Assistant Commissioner of Patents
Washington, D.C. 20231

PRELIMINARY AMENDMENT

S I R:

Prior to the issuance of an Office Action, please amend the application as follows:

IN THE CLAIMS

3. (Amended) A method according to claim 1, wherein said processing step is a cleaning step performed during, before and after a step that includes chemical mechanical polishing (CMP) for forming said wiring.

Please add the following new claim

12. (New) A method according to claim 2, wherein said processing step is a cleaning step performed during, before and after a step that includes chemical mechanical polishing (CMP) for forming said wiring.

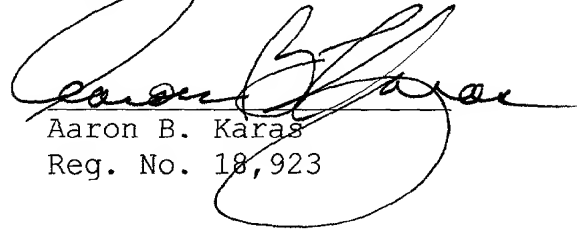
REMARKS

Attached hereto is a marked-up version of the changes made to the claims by the current amendment. The attached page is captioned **"Version with markings to show changes made."**

This amendment is being submitted to avoid multiple dependent claims.

Favorable consideration is respectfully requested.

Respectfully submitted



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VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE CLAIMS

3. (Amended) A method according to claim 1 ~~or 2~~, wherein said processing step is a cleaning step performed during, before and after a step that includes chemical mechanical polishing (CMP) for forming said wiring .